

Title (en)
TEMPERATURE CONTROL DEVICE AND METHOD FOR MANUFACTURING SAME

Title (de)
TEMPERATURSTEUERUNGSVORRICHTUNG UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)
DISPOSITIF DE RÉGULATION DE TEMPÉRATURE ET SON PROCÉDÉ DE FABRICATION

Publication
EP 2662655 A1 20131113 (EN)

Application
EP 11855235 A 20111226

Priority

- JP 2011002210 A 20110107
- JP 2011080124 W 20111226

Abstract (en)
A heat pipe (12) including a heat absorption part (12a) provided at one end side and absorbing heat from an outside and a heat dissipation part (12b) provided at another end side and dissipating heat to the outside, and a heat absorption plate (13) and a heat dissipation plate (14) (heat conducting plates) made of metal films formed by powder including metal being accelerated with a gas toward external surfaces of the heat absorption part (12a) and/or the heat dissipation part (12b) of the heat pipe (12) and being sprayed and deposited on the surfaces in a solid-phase state are provided.

IPC 8 full level
F28D 15/02 (2006.01)

CPC (source: EP US)
B21D 53/02 (2013.01 - US); **B22D 23/003** (2013.01 - EP US); **F28D 15/0275** (2013.01 - EP US); **F28D 15/046** (2013.01 - US); **H01L 23/427** (2013.01 - EP US); **H05K 7/20336** (2013.01 - EP US); **F28F 2255/00** (2013.01 - EP US); **F28F 2275/00** (2013.01 - EP US); **H01L 2924/0002** (2013.01 - EP US); **Y10T 29/49353** (2015.01 - EP US)

Citation (search report)
See references of WO 2012093613A1

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